



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20131004000
LM3445/LM3497 MSOP offload from TIEM to ASES for assembly and test
Change Notification / Sample Request

Date: 10/14/2013
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20131004000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LM3445MM/NOPB	null

Technical details of this Product Change follow on the next page(s).

PCN Number: 20131004000 **PCN Date:** 10/14/2013

Title: LM3445/LM3497 MSOP offload from TIEM to ASESH for assembly and test

Customer Contact: [PCN Manager](#) **Phone:** +1(214)480-6037 **Dept:** Quality Services

Proposed 1st Ship Date: 01/14/2014 **Estimated Sample Availability:** 10/31/2013

Change Type:		
<input checked="" type="checkbox"/>	Assembly Site	<input checked="" type="checkbox"/>
<input type="checkbox"/>	Design	<input type="checkbox"/>
<input type="checkbox"/>	Test Site	<input type="checkbox"/>
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>
<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>
<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>
<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>
<input type="checkbox"/>	Part number change	<input type="checkbox"/>

PCN Details

Description of Change:

Qualification of ASE Shanghai (ASESH) as an additional assembly/test site for selected devices in the MSOP package family. Material differences are noted below:

	TI Melaka	ASE Shanghai
Mold Compound	8096859	EN2000515
Mount Compound	8075531	EY1000063
Lead Finish	Matte Sn	NiPdAu

Upon expiry of this PCN TI will combine lead free solutions in a single standard part number, for example; LM3445MM/NOPB – can ship with both Matte Sn and NiPdAu.

Reason for Change:

Business Continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Assembly Site		
TI Melaka	Assembly Site Origin (22L)	ASO: CU6
ASEH	Assembly Site Origin (22L)	ASO: ASH

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
 MADE IN: Malaysia
 2DC: 20:
 MSL '2 /260C/1 YEAR SEAL DT
 MSL 1 /235C/UNLIM 03/29/04
 OPT:
 ITEM: 39
 LBL: 5A (L)TO:1750
 NiPdAu

(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483SI2
 (P)
 (2P) REV: (V) 0033317
 (20L) GSO: SHE (21L) CCO:USA
 (22L) ASO: MLA (23L) ACO: MYS

Topside Device marking:
 Assembly site code for TIEM= U
 Assembly site code for ASEH = A

G4 =
 G3= MATTE Sn

Product Affected:				
LM3445MM/NOPB	LM3445MMX/NOPB	LM3497MM/NOPB	LM3497MMX	
LM3445MM/S7002547	LM3445MMX/S7002546	LM3497MM/S7002611	LM3497MMX/NOPB	
LM3445MM/UKY8	LM3497MM	LM3497MM/UKY8	LM3497MMX/S7002539	
Qualification Data:				
This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.				
Qual Vehicle: LM3445MM/NOPB				
Package Construction Details				
Assembly Site:	ASESH	Mold Compound:	EN2000515	
# Pins-Designator, Family:	10, DGS	Mount Compound:	EY1000063	
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	Cu, 1.3mils	
Qualification:	<input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results			
Reliability Test	Conditions	Sample Size/Fail		
		Lot# 1	Lot# 2	Lot# 3
DOPL	Tj=125C (500hrs)	77/0	--	--
**Biased HAST	130C/85%RH 33.3psia (96 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
HTSL	150C (1000hrs)	77/0	--	--
ESDH	500V, 1000V, 1500V	3/0	--	--
ESDC	250V, 750V	3/0	--	--
Latch Up	25C, 125C, 150C	6/0	--	--
Notes ** - Preconditioning sequence: Level 1-260C.				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com